



Abstract of the Disclosure

A sensor array having a plurality of pixels each including a sensor element coupled to a sensor input (24) of an electronic processing circuit is fabricated by first forming an integrated circuit having at least one array of electronic processing circuits (25, 26) each having a respective sensor input (24) disposed with terminal nodes of the integrated circuit toward a first surface of the wafer. In respect of either each pixel or each terminal node, an electrically conductive via (31) is formed through the wafer (20) extending from either the respective sensor input (24) or from the respective terminal node to a second surface (28) of the wafer opposite the first surface. This allows each electrically conductive via (31) exposed at the second surface of the wafer to serve for connection thereto of either a sensor element or a terminal connection that is electrically connected through the electrically conductive via (31) to the respective sensor input or terminal node.